RELIABILITY REPORT

FOR

MAX3084CSA+

PLASTIC ENCAPSULATED DEVICES

November 5, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX3084CSA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim''s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim''s quality and reliability standards.

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I. Device Description

A. General

The MAX3080-MAX3089 high-speed transceivers for RS-485/RS-422 communication contain one driver and one receiver. These devices feature fail-safe circuitry, which guarantees a logic-high receiver output when the receiver inputs are open or shorted. This means that the receiver output will be a logic high if all transmitters on a terminated bus are disabled (high impedance). The MAX3080/MAX3081/MAX3082 feature reduced slew-rate drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free data transmission up to 115kbps. The MAX3083/MAX3084/MAX3085 offer higher driver output slew-rate limits, allowing transmit speeds up to 500kbps. The MAX3086/MAX3087/MAX3088's driver slew rates are not limited, making transmit speeds up to 10Mbps possible. The MAX3089's slew rate is selectable between 115kbps, 500kbps, and 10Mbps by driving a selector pin with a single three-state driver. These transceivers typically draw 375µA of supply current when unloaded, or when fully loaded with the drivers disabled. All devices have a 1/8-unit-load receiver input impedance that allows up to 256 transceivers on the bus. The MAX3082/MAX3085/MAX3088 are intended for halfduplex communications, while the MAX3080/MAX3081/ MAX3083/MAX3084/MAX3086/MAX3087 are intended for full-duplex communications. The MAX3089 is selectable between half-duplex and full-duplex operation. It also features independently programmable receiver and transmitter output phase via separate pins.

II. Manufacturing Information

A. Description/Function:	Fail-Safe, High-Speed (10Mbps), Slew-Rate-Limited RS-485/RS-422 Transceivers
B. Process:	B3
C. Number of Device Transistors:	631
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1901-0156
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

IV. Die Information

A. Dimensions:	136 X 85 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 610 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 3.12 \times 10^{-9}$

λ = 3.12 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B3 Process results in a FIT Rate of 0.51 @ 25C and 8.79 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RS46-4 die type has been found to have all pins able to withstand a HBM transient pulse of +/-3000 per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX3084CSA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	610	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data